

China 3D IC and 2.5D IC Packaging Market Research Report 2018

<https://marketpublishers.com/r/CED8805031BEN.html>

Date: February 2018

Pages: 96

Price: US\$ 3,400.00 (Single User License)

ID: CED8805031BEN

Abstracts

The global 3D IC and 2.5D IC Packaging market is valued at XX million USD in 2016 and is expected to reach XX million USD by the end of 2022, growing at a CAGR of XX% between 2016 and 2022.

China plays an important role in global market, with market size of xx million USD in 2016 and will be xx million USD in 2022, with a CAGR of xx%.

This report studies the 3D IC and 2.5D IC Packaging development status and future trend in China, focuses on top players in China, also splits 3D IC and 2.5D IC Packaging by type and by applications, to fully and deeply research and reveal the market general situation and future forecast.

The major players in China market include

Taiwan Semiconductor

Samsung Electronics

Toshiba Corp

Advanced Semiconductor Engineering

Amkor Technology

Geographically, this report splits the China market into six regions,

South China

East China

Southwest China

Northeast China

North China

Central China

Northwest China

On the basis of product, this report displays the sales volume (Units), revenue (Million USD), product price (K USD/Unit), market share and growth rate of each type, primarily split into

3D wafer-level chip-scale packaging

3D TSV

2.5D

On the basis of the end users/application, this report covers

Logic

Imaging & optoelectronics

Memory

MEMS/sensors

LED

Power

If you have any special requirements, please let us know and we will offer you the report as you want.

Contents

China 3D IC and 2.5D IC Packaging Market Research Report 2017

1 3D IC AND 2.5D IC PACKAGING OVERVIEW

- 1.1 Product Overview and Scope of 3D IC and 2.5D IC Packaging
- 1.2 Classification of 3D IC and 2.5D IC Packaging by Product Category
 - 1.2.1 China 3D IC and 2.5D IC Packaging Sales (Units) Comparison by Type (2012-2022)
 - 1.2.2 China 3D IC and 2.5D IC Packaging Sales (Units) Market Share by Type in 2016
 - 1.2.3 3D wafer-level chip-scale packaging
 - 1.2.4 3D TSV
 - 1.2.5 2.5D
- 1.3 China 3D IC and 2.5D IC Packaging Market by Application/End Users
 - 1.3.1 China 3D IC and 2.5D IC Packaging Sales (Units) and Market Share Comparison by Applications (2012-2022)
 - 1.3.2 Logic
 - 1.3.3 Imaging & optoelectronics
 - 1.3.4 Memory
 - 1.3.5 MEMS/sensors
 - 1.3.6 LED
 - 1.3.7 Power
- 1.4 China 3D IC and 2.5D IC Packaging Market by Region
 - 1.4.1 China 3D IC and 2.5D IC Packaging Market Size (Million USD) Comparison by Region (2012-2022)
 - 1.4.2 South China 3D IC and 2.5D IC Packaging Status and Prospect (2012-2022)
 - 1.4.3 East China 3D IC and 2.5D IC Packaging Status and Prospect (2012-2022)
 - 1.4.4 Southwest China 3D IC and 2.5D IC Packaging Status and Prospect (2012-2022)
 - 1.4.5 Northeast China 3D IC and 2.5D IC Packaging Status and Prospect (2012-2022)
 - 1.4.6 North China 3D IC and 2.5D IC Packaging Status and Prospect (2012-2022)
 - 1.4.7 Central China 3D IC and 2.5D IC Packaging Status and Prospect (2012-2022)
- 1.5 China Market Size (Sales and Revenue) of 3D IC and 2.5D IC Packaging (2012-2022)
 - 1.5.1 China 3D IC and 2.5D IC Packaging Sales (Units) and Growth Rate (%) (2012-2022)
 - 1.5.2 China 3D IC and 2.5D IC Packaging Revenue (Million USD) and Growth Rate (%) (2012-2022)

2 CHINA 3D IC AND 2.5D IC PACKAGING MARKET COMPETITION BY PLAYERS/MANUFACTURERS

2.1 China 3D IC and 2.5D IC Packaging Sales and Market Share of Key Players/Manufacturers (2012-2017)

2.2 China 3D IC and 2.5D IC Packaging Revenue and Share by Players/Manufacturers (2012-2017)

2.3 China 3D IC and 2.5D IC Packaging Average Price (K USD/Unit) by Players/Manufacturers (2012-2017)

2.4 China 3D IC and 2.5D IC Packaging Market Competitive Situation and Trends

2.4.1 China 3D IC and 2.5D IC Packaging Market Concentration Rate

2.4.2 China 3D IC and 2.5D IC Packaging Market Share of Top 3 and Top 5 Players/Manufacturers

2.4.3 Mergers & Acquisitions, Expansion in China Market

2.5 China Players/Manufacturers 3D IC and 2.5D IC Packaging Manufacturing Base Distribution, Sales Area, Product Types

3 CHINA 3D IC AND 2.5D IC PACKAGING SALES AND REVENUE BY REGION (2012-2017)

3.1 China 3D IC and 2.5D IC Packaging Sales (Units) and Market Share by Region (2012-2017)

3.2 China 3D IC and 2.5D IC Packaging Revenue (Million USD) and Market Share by Region (2012-2017)

3.3 China 3D IC and 2.5D IC Packaging Price (K USD/Unit) by Regions (2012-2017)

4 CHINA '&B1&' SALES AND REVENUE BY TYPE/ PRODUCT CATEGORY (2012-2017)'

4.1 China 3D IC and 2.5D IC Packaging Sales (Units) and Market Share by Type/ Product Category (2012-2017)

4.2 China 3D IC and 2.5D IC Packaging Revenue (Million USD) and Market Share by Type (2012-2017)

4.3 China 3D IC and 2.5D IC Packaging Price (K USD/Unit) by Type (2012-2017)

4.4 China 3D IC and 2.5D IC Packaging Sales Growth Rate (%) by Type (2012-2017)

5 CHINA '&B1&' SALES BY APPLICATION (2012-2017)'

5.1 China 3D IC and 2.5D IC Packaging Sales (Units) and Market Share by Application (2012-2017)

5.2 China 3D IC and 2.5D IC Packaging Sales Growth Rate (%) by Application (2012-2017)

5.3 Market Drivers and Opportunities

6 CHINA 3D IC AND 2.5D IC PACKAGING PLAYERS/SUPPLIERS PROFILES AND SALES DATA

6.1 Taiwan Semiconductor

6.1.1 Company Basic Information, Manufacturing Base and Competitors

6.1.2 3D IC and 2.5D IC Packaging Product Category, Application and Specification

6.1.2.1 Product A

6.1.2.2 Product B

6.1.3 Taiwan Semiconductor 3D IC and 2.5D IC Packaging Sales (Units), Revenue (Million USD), Price (K USD/Unit) and Gross Margin (%) (2012-2017)

6.1.4 Main Business/Business Overview

6.2 Samsung Electronics

6.2.1 Company Basic Information, Manufacturing Base and Competitors

6.2.2 3D IC and 2.5D IC Packaging Product Category, Application and Specification

6.2.2.1 Product A

6.2.2.2 Product B

6.2.3 Samsung Electronics 3D IC and 2.5D IC Packaging Sales (Units), Revenue (Million USD), Price (K USD/Unit) and Gross Margin (%) (2012-2017)

6.2.4 Main Business/Business Overview

6.3 Toshiba Corp

6.3.1 Company Basic Information, Manufacturing Base and Competitors

6.3.2 3D IC and 2.5D IC Packaging Product Category, Application and Specification

6.3.2.1 Product A

6.3.2.2 Product B

6.3.3 Toshiba Corp 3D IC and 2.5D IC Packaging Sales (Units), Revenue (Million USD), Price (K USD/Unit) and Gross Margin (%) (2012-2017)

6.3.4 Main Business/Business Overview

6.4 Advanced Semiconductor Engineering

6.4.1 Company Basic Information, Manufacturing Base and Competitors

6.4.2 3D IC and 2.5D IC Packaging Product Category, Application and Specification

6.4.2.1 Product A

6.4.2.2 Product B

6.4.3 Advanced Semiconductor Engineering 3D IC and 2.5D IC Packaging Sales

(Units), Revenue (Million USD), Price (K USD/Unit) and Gross Margin (%) (2012-2017)

6.4.4 Main Business/Business Overview

6.5 Amkor Technology

6.5.1 Company Basic Information, Manufacturing Base and Competitors

6.5.2 3D IC and 2.5D IC Packaging Product Category, Application and Specification

6.5.2.1 Product A

6.5.2.2 Product B

6.5.3 Amkor Technology 3D IC and 2.5D IC Packaging Sales (Units), Revenue (Million USD), Price (K USD/Unit) and Gross Margin (%) (2012-2017)

6.5.4 Main Business/Business Overview

7 3D IC AND 2.5D IC PACKAGING MANUFACTURING COST ANALYSIS

7.1 3D IC and 2.5D IC Packaging Key Raw Materials Analysis

7.1.1 Key Raw Materials

7.1.2 Price Trend of Key Raw Materials

7.1.3 Key Suppliers of Raw Materials

7.1.4 Market Concentration Rate of Raw Materials

7.2 Proportion of Manufacturing Cost Structure

7.2.1 Raw Materials

7.2.2 Labor Cost

7.2.3 Manufacturing Expenses

7.3 Manufacturing Process Analysis of 3D IC and 2.5D IC Packaging

8 INDUSTRIAL CHAIN, SOURCING STRATEGY AND DOWNSTREAM BUYERS

8.1 3D IC and 2.5D IC Packaging Industrial Chain Analysis

8.2 Upstream Raw Materials Sourcing

8.3 Raw Materials Sources of 3D IC and 2.5D IC Packaging Major Manufacturers in 2016

8.4 Downstream Buyers

9 MARKETING STRATEGY ANALYSIS, DISTRIBUTORS/TRADERS

9.1 Marketing Channel

9.1.1 Direct Marketing

9.1.2 Indirect Marketing

9.1.3 Marketing Channel Development Trend

9.2 Market Positioning

- 9.2.1 Pricing Strategy
- 9.2.2 Brand Strategy
- 9.2.3 Target Client
- 9.3 Distributors/Traders List

10 MARKET EFFECT FACTORS ANALYSIS

- 10.1 Technology Progress/Risk
 - 10.1.1 Substitutes Threat
 - 10.1.2 Technology Progress in Related Industry
- 10.2 Consumer Needs/Customer Preference Change
- 10.3 Economic/Political Environmental Change

11 CHINA 3D IC AND 2.5D IC PACKAGING MARKET SIZE (SALES AND REVENUE) FORECAST (2017-2022)

- 11.1 China 3D IC and 2.5D IC Packaging Sales (Units), Revenue (Million USD) Forecast (2017-2022)
- 11.2 China 3D IC and 2.5D IC Packaging Sales (Units) Forecast by Type (2017-2022)
- 11.3 China 3D IC and 2.5D IC Packaging Sales (Units) Forecast by Application (2017-2022)
- 11.4 China 3D IC and 2.5D IC Packaging Sales (Units) Forecast by Region (2017-2022)

12 RESEARCH FINDINGS AND CONCLUSION

13 METHODOLOGY AND DATA SOURCE

- 13.1 Methodology/Research Approach
 - 13.1.1 Research Programs/Design
 - 13.1.2 Market Size Estimation
 - 13.1.3 Market Breakdown and Data Triangulation
- 13.2 Data Source
 - 13.2.1 Secondary Sources
 - 13.2.2 Primary Sources
- 13.3 Disclaimer
- 13.4 Author List

The report requires updating with new data and is sent in 2-3 business days after order is placed.

List Of Tables

LIST OF TABLES AND FIGURES

Figure Global and China Market Size (Million USD) Comparison (2012-2022)
Table 3D IC and 2.5D IC Packaging Sales (Units) and Revenue (Million USD) Market Split by Product Type
Table 3D IC and 2.5D IC Packaging Sales (Units) by Application (2016-2022)
Figure Product Picture of 3D IC and 2.5D IC Packaging
Table China 3D IC and 2.5D IC Packaging Sales (Units) and Growth Rate (%) Comparison by Types (Product Category) (2012-2022)
Figure China 3D IC and 2.5D IC Packaging Sales Volume Market Share by Types in 2016
Figure 3D wafer-level chip-scale packaging Product Picture
Figure 3D TSV Product Picture
Figure 2.5D Product Picture
Figure China 3D IC and 2.5D IC Packaging Sales (Units) Comparison by Application (2012-2022)
Figure China Sales Market Share (%) of 3D IC and 2.5D IC Packaging by Application in 2016
Figure Logic Examples
Table Key Downstream Customer in Logic
Figure Imaging & optoelectronics Examples
Table Key Downstream Customer in Imaging & optoelectronics
Figure Memory Examples
Table Key Downstream Customer in Memory
Figure MEMS/sensors Examples
Table Key Downstream Customer in MEMS/sensors
Figure LED Examples
Table Key Downstream Customer in LED
Figure Power Examples
Table Key Downstream Customer in Power
Figure South China 3D IC and 2.5D IC Packaging Revenue (Million USD) and Growth Rate (2012-2022)
Figure East China 3D IC and 2.5D IC Packaging Revenue (Million USD) and Growth Rate (2012-2022)
Figure Southwest China 3D IC and 2.5D IC Packaging Revenue (Million USD) and Growth Rate (2012-2022)
Figure Northeast China 3D IC and 2.5D IC Packaging Revenue (Million USD) and

Growth Rate (2012-2022)

Figure North China 3D IC and 2.5D IC Packaging Revenue (Million USD) and Growth Rate (2012-2022)

Figure Central China 3D IC and 2.5D IC Packaging Revenue (Million USD) and Growth Rate (2012-2022)

Figure China 3D IC and 2.5D IC Packaging Sales (Units) and Growth Rate (%) (2012-2022)

Figure China 3D IC and 2.5D IC Packaging Revenue (Million USD) and Growth Rate (%) (2012-2022)

Table China 3D IC and 2.5D IC Packaging Sales of Key Players/Manufacturers (2012-2017)

Table China 3D IC and 2.5D IC Packaging Sales Share (%) by Players/Manufacturers (2012-2017)

Figure 2016 China 3D IC and 2.5D IC Packaging Sales Share (%) by Players/Manufacturers

Figure 2017 China 3D IC and 2.5D IC Packaging Sales Share (%) by Players/Manufacturers

Table China 3D IC and 2.5D IC Packaging Revenue by Players/Manufacturers (2012-2017)

Table China 3D IC and 2.5D IC Packaging Revenue Market Share (%) by Players/Manufacturers (2012-2017)

Figure 2016 China 3D IC and 2.5D IC Packaging Revenue Market Share (%) by Players/Manufacturers

Figure 2017 China 3D IC and 2.5D IC Packaging Revenue Market Share (%) by Players/Manufacturers

Table China Market 3D IC and 2.5D IC Packaging Average Price of Key Players/Manufacturers (2012-2017)

Figure China Market 3D IC and 2.5D IC Packaging Average Price of Key Players/Manufacturers in 2016

Figure China 3D IC and 2.5D IC Packaging Market Share of Top 3 Players/Manufacturers

Figure China 3D IC and 2.5D IC Packaging Market Share of Top 5 Players/Manufacturers

Table China Players/Manufacturers 3D IC and 2.5D IC Packaging Manufacturing Base Distribution and Sales Area

Table China Players/Manufacturers 3D IC and 2.5D IC Packaging Product Category

Table China 3D IC and 2.5D IC Packaging Sales (Units) by Regions (2012-2017)

Table China 3D IC and 2.5D IC Packaging Sales Share (%) by Regions (2012-2017)

Figure China 3D IC and 2.5D IC Packaging Sales Share (%) by Regions (2012-2017)

Figure China 3D IC and 2.5D IC Packaging Sales Market Share (%) by Regions in 2016
Table China 3D IC and 2.5D IC Packaging Revenue (Million USD) and Market Share by Regions (2012-2017)

Table China 3D IC and 2.5D IC Packaging Revenue Market Share (%) by Regions (2012-2017)

Figure China 3D IC and 2.5D IC Packaging Revenue Market Share (%) by Regions (2012-2017)

Figure China 3D IC and 2.5D IC Packaging Revenue Market Share (%) by Regions in 2016

Table China 3D IC and 2.5D IC Packaging Price (K USD/Unit) by Regions (2012-2017)

Table China 3D IC and 2.5D IC Packaging Sales (Units) by Type (2012-2017)

Table China 3D IC and 2.5D IC Packaging Sales Share (%) by Type (2012-2017)

Figure China 3D IC and 2.5D IC Packaging Sales Share (%) by Type (2012-2017)

Figure China 3D IC and 2.5D IC Packaging Sales Market Share (%) by Type in 2016

Table China 3D IC and 2.5D IC Packaging Revenue (Million USD) and Market Share by Type (2012-2017)

Table China 3D IC and 2.5D IC Packaging Revenue Market Share (%) by Type (2012-2017)

Figure Revenue Market Share of 3D IC and 2.5D IC Packaging by Type (2012-2017)

Figure Revenue Market Share of 3D IC and 2.5D IC Packaging by Type in 2016

Table China 3D IC and 2.5D IC Packaging Price (K USD/Unit) by Types (2012-2017)

Figure China 3D IC and 2.5D IC Packaging Sales Growth Rate (%) by Type (2012-2017)

Table China 3D IC and 2.5D IC Packaging Sales (Units) by Applications (2012-2017)

Table China 3D IC and 2.5D IC Packaging Sales Market Share (%) by Applications (2012-2017)

Figure China 3D IC and 2.5D IC Packaging Sales Market Share (%) by Application (2012-2017)

Figure China 3D IC and 2.5D IC Packaging Sales Market Share (%) by Application in 2016

Table China 3D IC and 2.5D IC Packaging Sales Growth Rate (%) by Application (2012-2017)

Figure China 3D IC and 2.5D IC Packaging Sales Growth Rate (%) by Application (2012-2017)

Table Taiwan Semiconductor 3D IC and 2.5D IC Packaging Basic Information List

Table Taiwan Semiconductor 3D IC and 2.5D IC Packaging Sales (Units), Revenue (Million USD), Price (K USD/Unit) and Gross Margin (%) (2012-2017)

Figure Taiwan Semiconductor 3D IC and 2.5D IC Packaging Sales (Units) and Growth Rate (%) (2012-2017)

Figure Taiwan Semiconductor 3D IC and 2.5D IC Packaging Sales Market Share (%) in China (2012-2017)

Figure Taiwan Semiconductor 3D IC and 2.5D IC Packaging Revenue Market Share (%) in China (2012-2017)

Table Samsung Electronics 3D IC and 2.5D IC Packaging Basic Information List

Table Samsung Electronics 3D IC and 2.5D IC Packaging Sales (Units), Revenue (Million USD), Price (K USD/Unit) and Gross Margin (%) (2012-2017)

Figure Samsung Electronics 3D IC and 2.5D IC Packaging Sales (Units) and Growth Rate (%) (2012-2017)

Figure Samsung Electronics 3D IC and 2.5D IC Packaging Sales Market Share (%) in China (2012-2017)

Figure Samsung Electronics 3D IC and 2.5D IC Packaging Revenue Market Share (%) in China (2012-2017)

Table Toshiba Corp 3D IC and 2.5D IC Packaging Basic Information List

Table Toshiba Corp 3D IC and 2.5D IC Packaging Sales (Units), Revenue (Million USD), Price (K USD/Unit) and Gross Margin (%) (2012-2017)

Figure Toshiba Corp 3D IC and 2.5D IC Packaging Sales (Units) and Growth Rate (%) (2012-2017)

Figure Toshiba Corp 3D IC and 2.5D IC Packaging Sales Market Share (%) in China (2012-2017)

Figure Toshiba Corp 3D IC and 2.5D IC Packaging Revenue Market Share (%) in China (2012-2017)

Table Advanced Semiconductor Engineering 3D IC and 2.5D IC Packaging Basic Information List

Table Advanced Semiconductor Engineering 3D IC and 2.5D IC Packaging Sales (Units), Revenue (Million USD), Price (K USD/Unit) and Gross Margin (%) (2012-2017)

Figure Advanced Semiconductor Engineering 3D IC and 2.5D IC Packaging Sales (Units) and Growth Rate (%) (2012-2017)

Figure Advanced Semiconductor Engineering 3D IC and 2.5D IC Packaging Sales Market Share (%) in China (2012-2017)

Figure Advanced Semiconductor Engineering 3D IC and 2.5D IC Packaging Revenue Market Share (%) in China (2012-2017)

Table Amkor Technology 3D IC and 2.5D IC Packaging Basic Information List

Table Amkor Technology 3D IC and 2.5D IC Packaging Sales (Units), Revenue (Million USD), Price (K USD/Unit) and Gross Margin (%) (2012-2017)

Figure Amkor Technology 3D IC and 2.5D IC Packaging Sales (Units) and Growth Rate (%) (2012-2017)

Figure Amkor Technology 3D IC and 2.5D IC Packaging Sales Market Share (%) in China (2012-2017)

Figure Amkor Technology 3D IC and 2.5D IC Packaging Revenue Market Share (%) in China (2012-2017)

Table Production Base and Market Concentration Rate of Raw Material

Figure Price Trend of Key Raw Materials

Table Key Suppliers of Raw Materials

Figure Manufacturing Cost Structure of 3D IC and 2.5D IC Packaging

Figure Manufacturing Process Analysis of 3D IC and 2.5D IC Packaging

Figure 3D IC and 2.5D IC Packaging Industrial Chain Analysis

Table Raw Materials Sources of 3D IC and 2.5D IC Packaging Major Players/Manufacturers in 2016

Table Major Buyers of 3D IC and 2.5D IC Packaging

Table Distributors/Traders List

Figure China 3D IC and 2.5D IC Packaging Sales (Units) and Growth Rate (%) Forecast (2017-2022)

Figure China 3D IC and 2.5D IC Packaging Revenue (Million USD) and Growth Rate Forecast (2017-2022)

Figure China 3D IC and 2.5D IC Packaging Price (K USD/Unit) Trend Forecast (2017-2022)

Table China 3D IC and 2.5D IC Packaging Sales (Units) Forecast by Type (2017-2022)

Figure China 3D IC and 2.5D IC Packaging Sales (Units) Forecast by Type (2017-2022)

Figure China 3D IC and 2.5D IC Packaging Sales Volume Market Share Forecast by Type in 2022

Table China 3D IC and 2.5D IC Packaging Sales (Units) Forecast by Application (2017-2022)

Figure China 3D IC and 2.5D IC Packaging Sales Volume Market Share Forecast by Application (2017-2022)

Figure China 3D IC and 2.5D IC Packaging Sales Volume Market Share Forecast by Application in 2022

Table China 3D IC and 2.5D IC Packaging Sales (Units) Forecast by Regions (2017-2022)

Table China 3D IC and 2.5D IC Packaging Sales Volume Share Forecast by Regions (2017-2022)

Figure China 3D IC and 2.5D IC Packaging Sales Volume Share Forecast by Regions (2017-2022)

Figure China 3D IC and 2.5D IC Packaging Sales Volume Share Forecast by Regions in 2022

Table Research Programs/Design for This Report

Figure Bottom-up and Top-down Approaches for This Report

Figure Data Triangulation

Table Key Data Information from Secondary Sources

Table Key Data Information from Primary Sources

I would like to order

Product name: China 3D IC and 2.5D IC Packaging Market Research Report 2018

Product link: <https://marketpublishers.com/r/CED8805031BEN.html>

Price: US\$ 3,400.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:

info@marketpublishers.com

Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page <https://marketpublishers.com/r/CED8805031BEN.html>

To pay by Wire Transfer, please, fill in your contact details in the form below:

First name:
Last name:
Email:
Company:
Address:
City:
Zip code:
Country:
Tel:
Fax:
Your message:

****All fields are required**

Customer signature _____

Please, note that by ordering from marketpublishers.com you are agreeing to our Terms & Conditions at <https://marketpublishers.com/docs/terms.html>

To place an order via fax simply print this form, fill in the information below and fax the completed form to +44 20 7900 3970